The new, innovative way of dispensing





Part of the Atlas Copco Group

DosPL DPL2001



Product data DosPL DPL2001

	1C	20
Volume/shot at 1:1 min.¹ [ml]	0.003	0.006
Volume/shot at 1:1 max.1 [ml]	2	4
Outlets	1	
Dimensions (W x D x H) [mm]	271 x 170 x 670	335 x 190 x 670
Weight [kg]	8.2	15.1

¹ application dependent

Technical changes reserved.

Low volume applications



Fixation Bonding

Optic components, electronic components on PCB, screw fittings



Heat Dissipation

ECUs, power semiconductors, charging stations, LEDs



Potting

LEDs, connectors, sensors, coils



Sealing

Enclosures, control units, sensors, connectors



Insulation

MEMS, integrated circuit boards, capacitors

The Allround Solution for Low Volume Applications

Whether bonding, sealing, filling or heat dissipation, their simple, robust design makes piston dispensers the systems of choice for many different tasks. They also cover a wide range of materials: In addition to very liquid adhesives, sealants and potting materials, piston dispensers are also suitable for highly viscous and/or filled as well as highly abrasive materials.

The DosPL DPL2001 can be used to dispense extremely small volumes down to a few µl. This means that dot sizes smaller than the head of a pin can be dispensed precisely. At the same time, the maximum cylinder filling of up to 4 ml with 2C materials ensures maximum flexibility. The DosPL DPL2001 is based on **#Advanced Low Volume Dispensing** technology, which makes it the right choice for a wide range of smaller component designs and applications.

The volumetric piston dispensing principle, in combination with the advanced sensor technology, ensures highest precision and process reliability during dispensing. The smallest dots and thinnest lines as well as accurate micro-fillings can thus be reliably performed. High dispensing speeds and extended service lives contribute to maximum efficiency in fully automated production environments. Low volume dispensing is always the result of a sensible combination of innovative detailed solutions and process know-how.